



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Manabu MIZUSAKI

Serial No. 09/847,370

Filed May 3, 2001

ELECTRODE STRUCTURE OF A  
CARRIER SUBSTRATE OF  
SEMICONDUCTOR DEVICE

Confirmation No. 7669

GROUP 2827

Examiner James M. Mitchell

AMENDMENT

Commissioner for Patents

Washington, D.C. 20231

Sir:

Responsive to the Official Action of July 10, 2002,  
please amend the above-identified application as follows:

IN THE CLAIMS:

Amend claim 1 as follows:

C' --1. (twice amended) An electrode structure of a  
carrier substrate of a semiconductor device for solder-bonding  
the semiconductor device to a main substrate, said electrode  
structure comprising:

a carrier substrate having a recess in a central area  
of a surface thereof;

a soldering land of the electrode structure arranged in  
the recess, said soldering land having a circumferential wall  
defining a hollow portion extending from said surface, said  
circumferential wall being entirely within said recess; and

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